

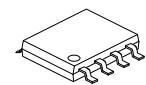
# UTT15N05

**Power MOSFET**

**15A, 50V N-CHANNEL  
ENHANCEMENT MODE**

## ■ DESCRIPTION

The **UTT15N05** uses UTC's advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with low gate voltages. This device is suitable for use as a load switch or in PWM applications.

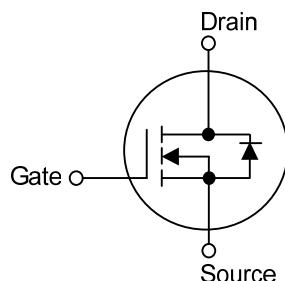


SOP-8

## ■ FEATURES

- \*  $R_{DS(ON)} < 55m\Omega$  @  $V_{GS}=10V$ ,  $I_D=7.5A$
- \*  $R_{DS(ON)} < 65m\Omega$  @  $V_{GS}=4.5V$ ,  $I_D=7.5A$
- \* Low capacitance
- \* Low gate charge
- \* Fast switching capability
- \* Avalanche energy specified

## ■ SYMBOL



## ■ ORDERING INFORMATION

Ordering Number		Package	Pin Assignment								Packing
Lead Free	Halogen Free		1	2	3	4	5	6	7	8	
UTT15N05L-S08-R	UTT15N05G-S08-R	SOP-8	S	S	S	G	D	D	D	D	Tape Reel

Note: Pin Assignment: G: Gate D: Drain S: Source

UTT15N05G-S08-R

(1)Packing Type

(2)Package Type

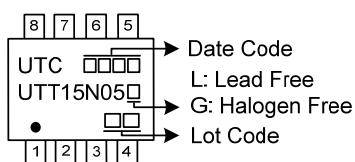
(3)Green Package

(1) R: Tape Reel

(2) S08: SOP-8

(3) G: Halogen Free and Lead Free, L: Lead Free

## ■ MARKING



■ ABSOLUTE MAXIMUM RATINGS ( $T_A=25^\circ\text{C}$ , unless otherwise specified)

PARAMETER	SYMBOL	RATINGS	UNIT
Drain-Source Voltage	$V_{DSS}$	50	V
Gate-Source Voltage	$V_{GSS}$	$\pm 20$	V
Continuous Drain Current	$I_D$	15	A
Pulsed Drain Current	$I_{DM}$	30	A
Repetitive avalanche energy ( $L=0.1\text{mH}$ )	$E_{AS}$	62	mJ
Power Dissipation ( $T_c=25^\circ\text{C}$ )	$P_D$	6	W
Junction Temperature	$T_J$	+150	$^\circ\text{C}$
Storage Temperature	$T_{STG}$	-55 ~ +150	$^\circ\text{C}$

Notes: 1. Absolute maximum ratings are those values beyond which the device could be permanently damaged.

Absolute maximum ratings are stress ratings only and functional device operation is not implied.

2. Repetitive Rating: Pulse width limited by maximum junction temperature.

3.  $L = 10\text{mH}$ ,  $I_{AS} = 3.53\text{A}$ ,  $V_{DD} = 50\text{V}$ ,  $R_G = 25\Omega$ , Starting  $T_J = 25^\circ\text{C}$ .

■ THERMAL DATA

PARAMETER	SYMBOL	RATINGS	UNIT
Junction-to-Ambient	$\theta_{JA}$	100	$^\circ\text{C}/\text{W}$
Junction to Case	$\theta_{JC}$	20.8 (Note)	$^\circ\text{C}/\text{W}$

Note: The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.

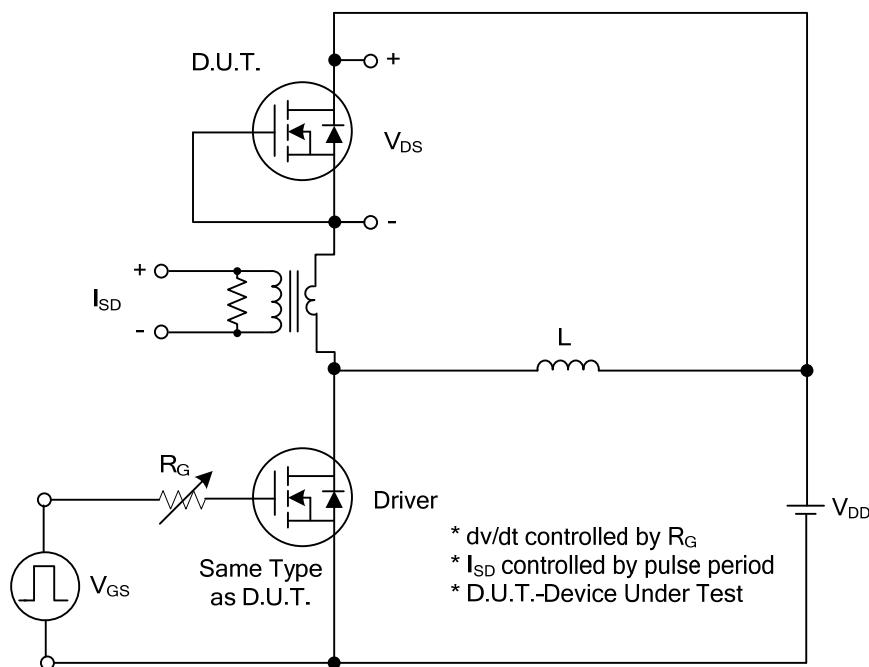
■ ELECTRICAL CHARACTERISTICS ( $T_J=25^\circ\text{C}$ , unless otherwise specified)

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNIT
<b>OFF CHARACTERISTICS</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0\text{V}$ , $I_D=250\mu\text{A}$	50			V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS}=50\text{V}$ , $V_{GS}=0\text{V}$			1	$\mu\text{A}$
Gate-Body Leakage Current	$I_{GSS}$	$V_{DS}=0\text{V}$ , $V_{GS}=\pm 20\text{V}$			100	nA
<b>ON CHARACTERISTICS</b>						
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{DS}=V_{GS}$ , $I_D=250\mu\text{A}$	1.0		3.0	V
Static Drain-Source On-Resistance	$R_{DS(ON)}$	$V_{GS}=10\text{V}$ , $I_D=7.5\text{A}$			55	$\text{m}\Omega$
		$V_{GS}=4.5\text{V}$ , $I_D=7.5\text{A}$			65	$\text{m}\Omega$
<b>DYNAMIC PARAMETERS</b>						
Input Capacitance	$C_{ISS}$	$V_{DS}=25\text{V}$ , $V_{GS}=0\text{V}$ , $f=1\text{MHz}$		574		pF
Output Capacitance	$C_{OSS}$			67		pF
Reverse Transfer Capacitance	$C_{RSS}$			57		pF
<b>SWITCHING PARAMETERS</b>						
Total Gate Charge	$Q_G$	$V_{DS}=25\text{V}$ , $V_{GS}=10\text{V}$ , $I_D=15\text{A}$ $I_G=1\text{mA}$		17		nC
Gate Source Charge	$Q_{GS}$			3.6		nC
Gate Drain Charge	$Q_{GD}$			3.1		nC
Turn-ON Delay Time	$t_{D(ON)}$	$V_{GS}=10\text{V}$ , $V_{DS}=30\text{V}$ , $I_D=0.5\text{A}$ , $R_G=3\Omega$		30		ns
Turn-ON Rise Time	$t_R$			34		ns
Turn-OFF Delay Time	$t_{D(OFF)}$			216		ns
Turn-OFF Fall-Time	$t_F$			126		ns
<b>SOURCE- DRAIN DIODE RATINGS AND CHARACTERISTICS</b>						
Maximum Body-Diode Continuous Current	$I_S$				15	A
Maximum Body-Diode Pulsed Current	$I_{SM}$				50	A
Diode Forward Voltage	$V_{SD}$	$I_S=15\text{A}$ , $V_{GS}=0\text{V}$			1.4	V
Body Diode Reverse Recovery Time	$t_{rr}$	$I_F=15\text{A}$ , $dI/dt=100\text{A}/\mu\text{s}$		68		ns
Body Diode Reverse Recovery Charge	$Q_{rr}$			22		nC

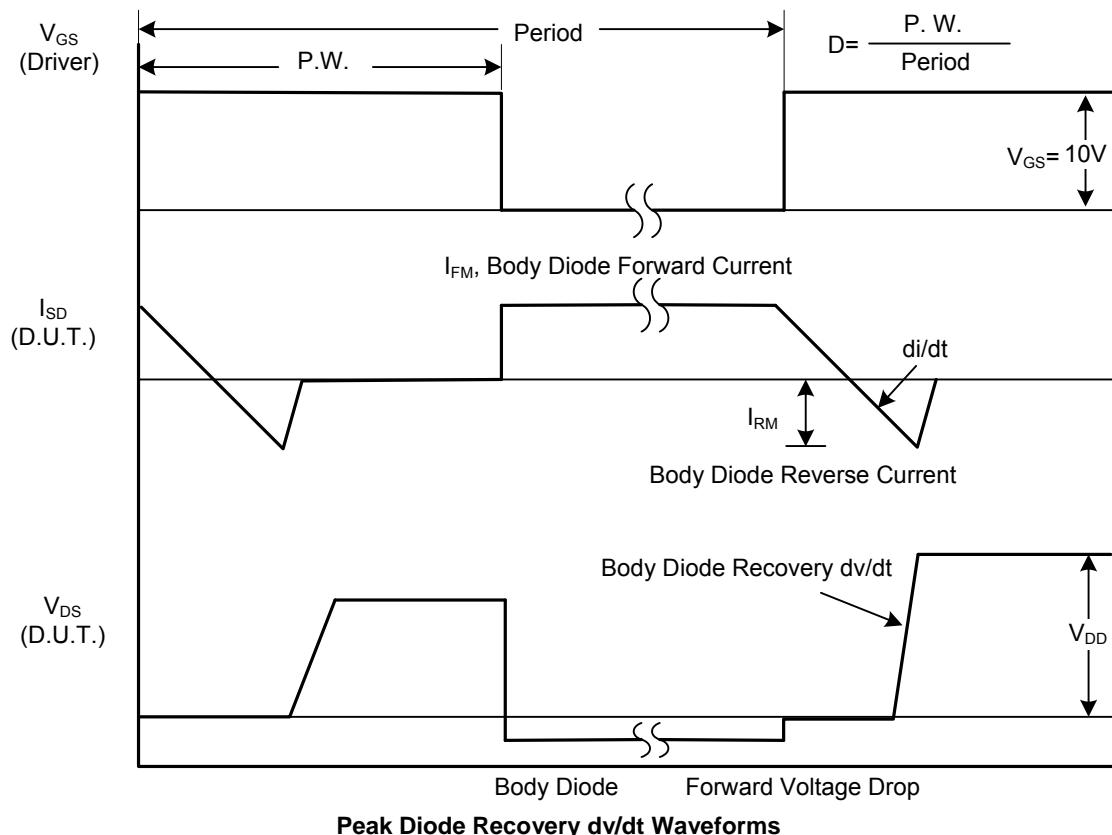
Notes: 1. The data tested by pulsed, pulse width  $\leq 500\mu\text{s}$ , duty cycles  $\leq 2\%$ .

2. The power dissipation is limited by  $150^\circ\text{C}$  junction temperature.

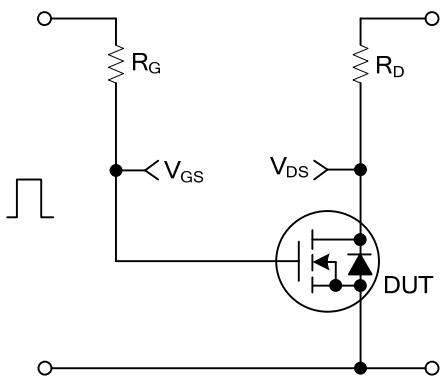
■ TEST CIRCUITS AND WAVEFORMS



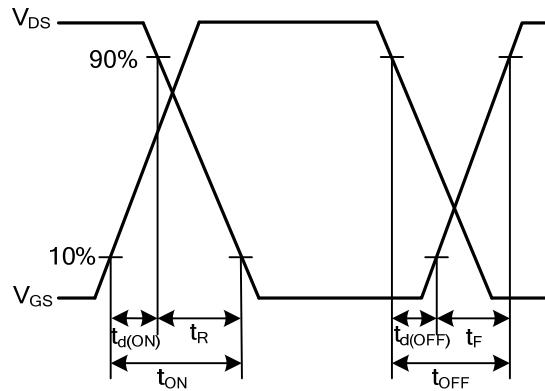
Peak Diode Recovery  $dv/dt$  Test Circuit



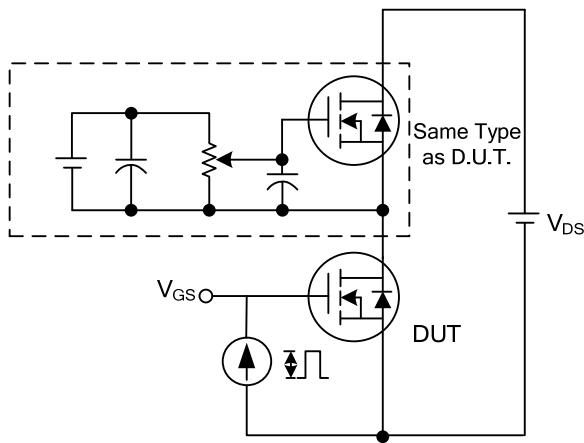
### ■ TEST CIRCUITS AND WAVEFORMS



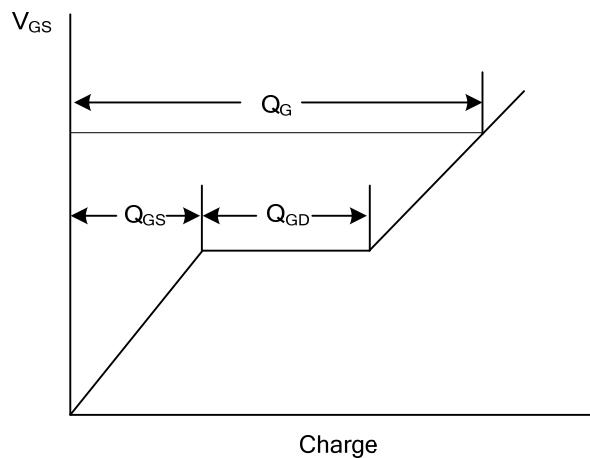
Latching Test Circuit



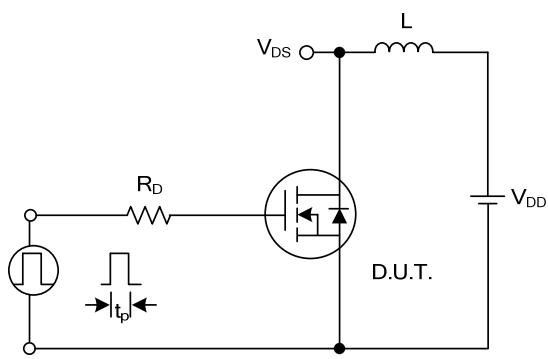
Switching Waveforms



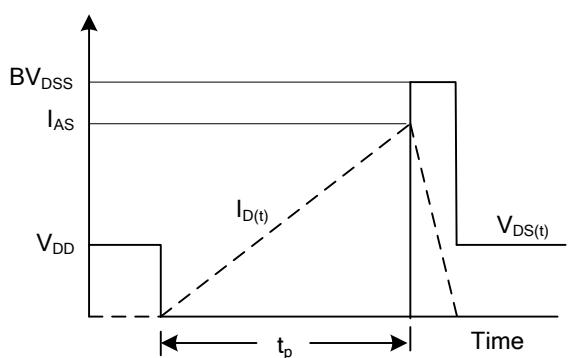
Gate Charge Test Circuit



Gate Charge Waveform

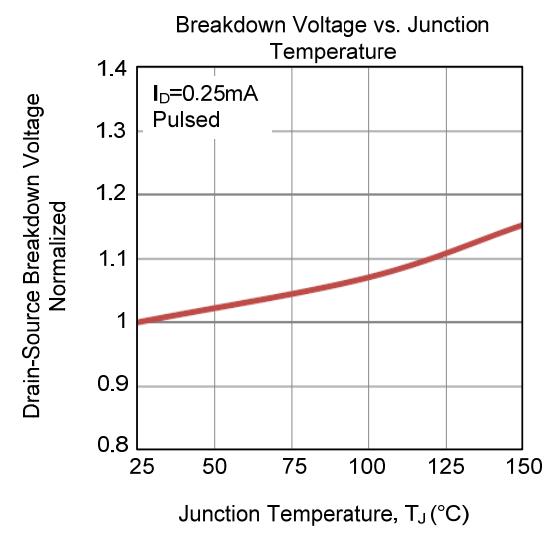
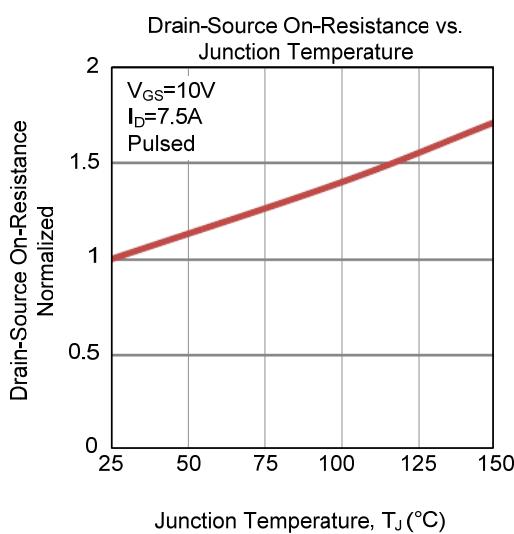
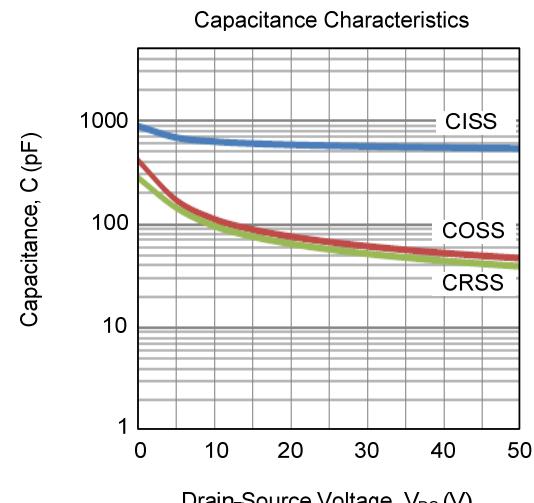
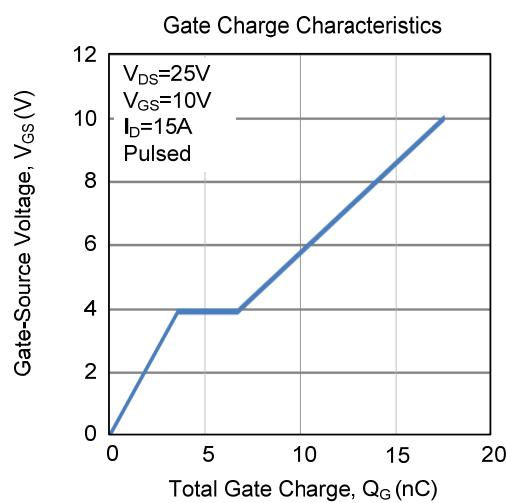
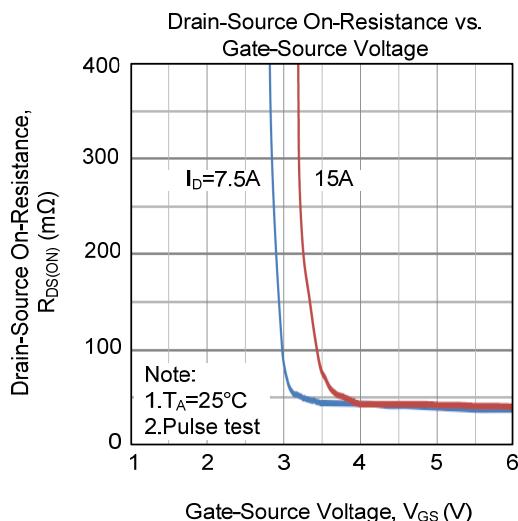
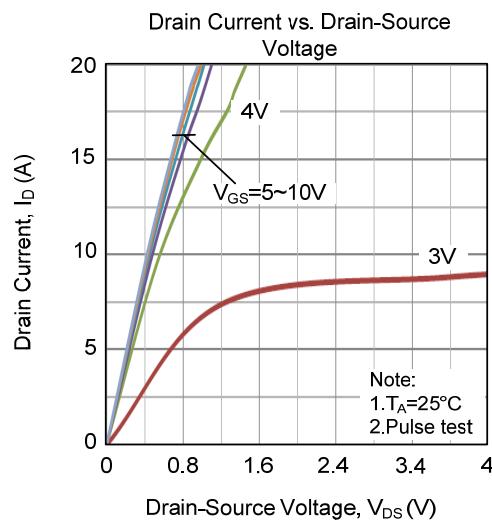


Unclamped Inductive Switching Test Circuit

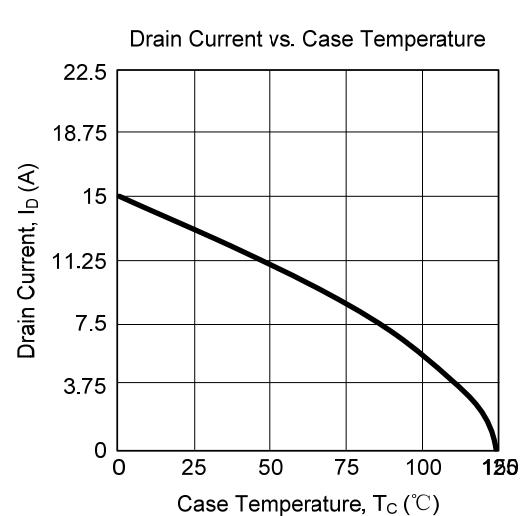
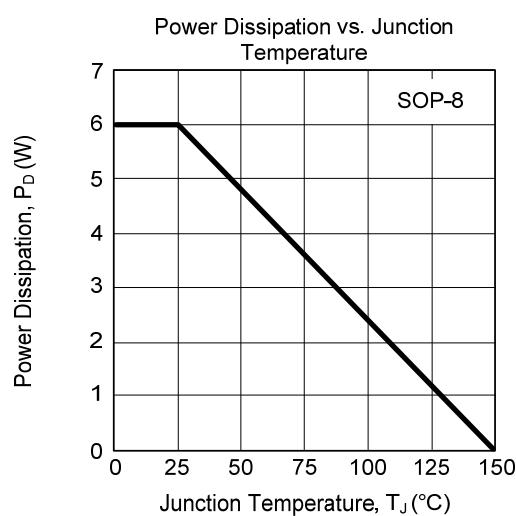
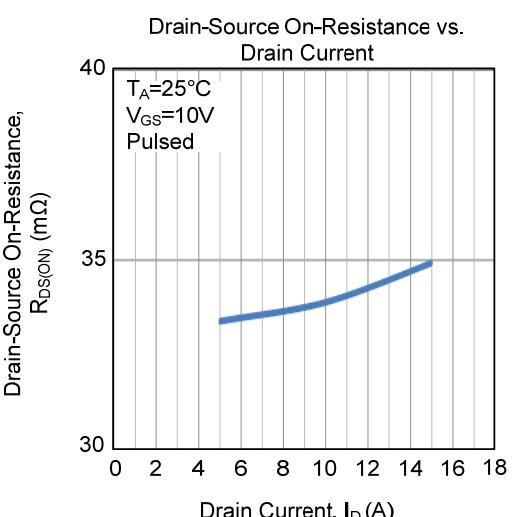
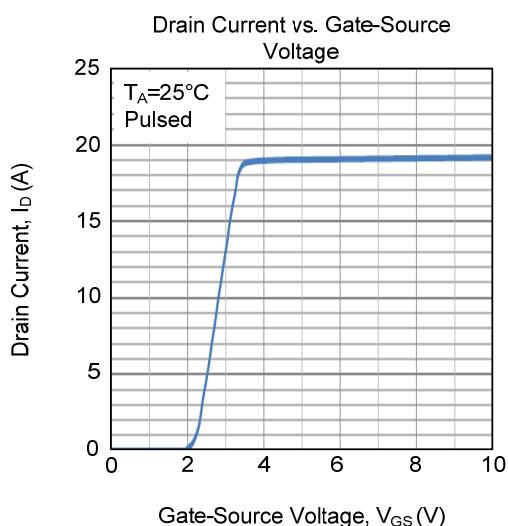
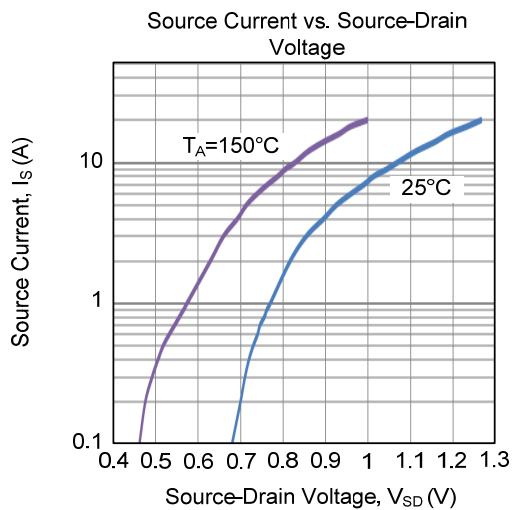
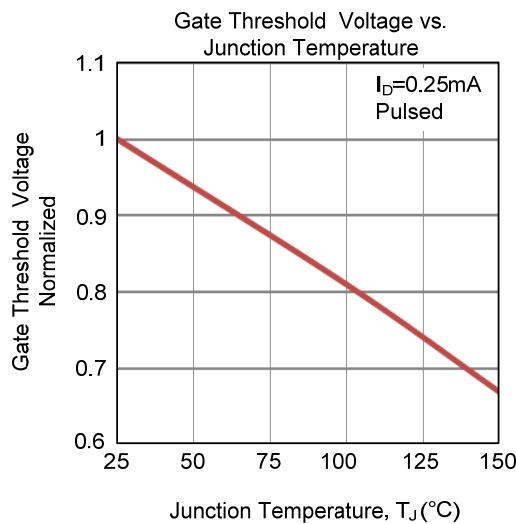


Unclamped Inductive Switching Waveforms

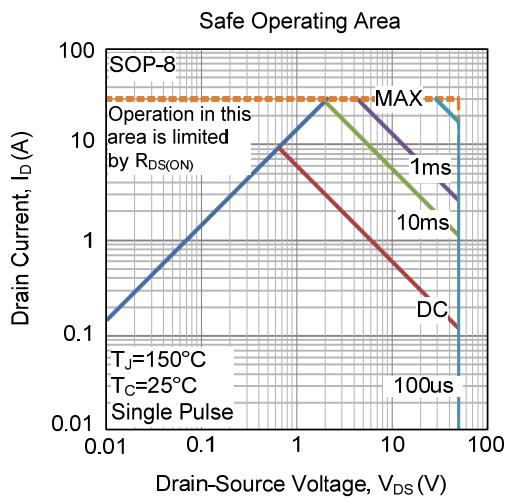
■ TYPICAL CHARACTERISTICS



■ TYPICAL CHARACTERISTICS (Cont.)



## ■ TYPICAL CHARACTERISTICS (Cont.)



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